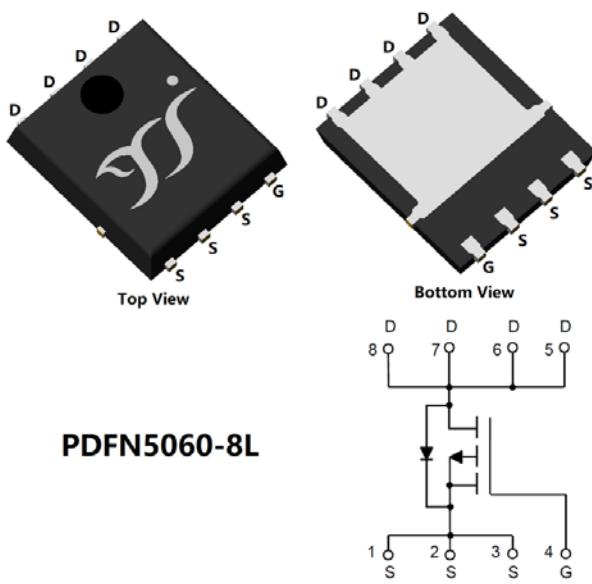


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} -60 V
- I_D -80 A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) $<8.5m\Omega$
- 100% UIS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Low $R_{DS(on)}$ & FOM
- Excellent stability and uniformity
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Power management
- Portable equipment
- 12 and 24V Automotive systems

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	-60	V
Gate-source Voltage	V_{GS}	± 18	V
Drain Current	I_D	-12	A
		-7.5	
		-80	
		-50	
Pulsed Drain Current ^A	I_{DM}	-320	A
Avalanche energy ^B	EAS	400	mJ
Total Power Dissipation ^C	P_D	2.5	W
		1	
		120	
		48	
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C

■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$R_{\theta JA}$	40	50	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.8	1.04	



■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG80GP06BQ	F1	YJG80GP06B	5000	10000	100000	13" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm18\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-2	-2.7	-4	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	-	6.1	8.5	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-20\text{A}, V_{\text{GS}}=0\text{V}$	-	-0.9	-1.3	V
Gate resistance	R_{G}	$f=1\text{MHz}, \text{Open drain}$	-	10	-	Ω
Maximum Body-Diode Continuous Current	I_{S}		-	-	-80	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	5500	-	pF
Output Capacitance	C_{oss}		-	1555	-	
Reverse Transfer Capacitance	C_{rss}		-	220	-	
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-30\text{V}, I_{\text{D}}=-20\text{A}$	-	80.7	-	nC
Gate-Source Charge	Q_{gs}		-	19	-	
Gate-Drain Charge	Q_{gd}		-	18.3	-	
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=-20\text{A}, \text{di/dt}=100\text{A/us}$	-	84	-	nC
Reverse Recovery Time	t_{rr}		-	57.5	-	
Turn-on Delay Time	$t_{\text{D(on)}}$		-	13.2	-	
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=-10\text{V}, V_{\text{DD}}=-30\text{V}, R_{\text{GEN}}=1.6\Omega, I_{\text{D}}=-20\text{A}$	-	27.7	-	ns
Turn-off Delay Time	$t_{\text{D(off)}}$		-	137.8	-	
Turn-off fall Time	t_{f}		-	59.5	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. $T_J=25^\circ\text{C}, V_{\text{DD}}=-40\text{V}, V_{\text{GS}}=-10\text{V}, L=2\text{mH}, I_{\text{AS}}=-20\text{A}$.

C. P_d is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.

D. The value of $R_{\theta,\text{JA}}$ is measured with the device mounted on the minimum recommend pad size, in the still air environment with $T_A=25^\circ\text{C}$. The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

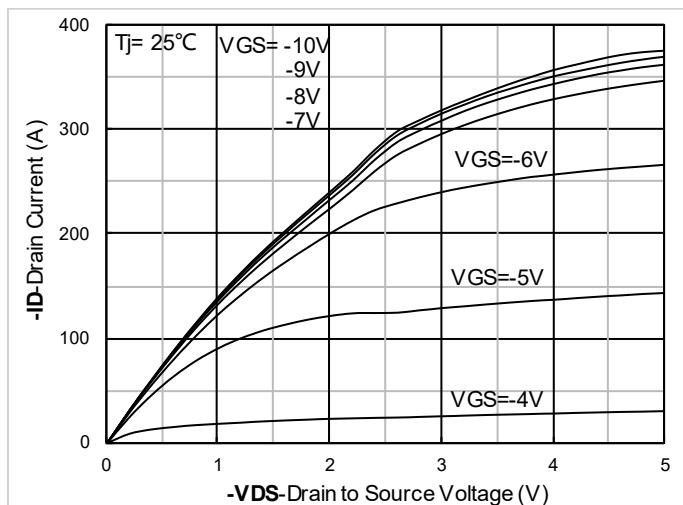
**■ Typical Electrical and Thermal Characteristics Diagrams**

Figure 1. Output Characteristics

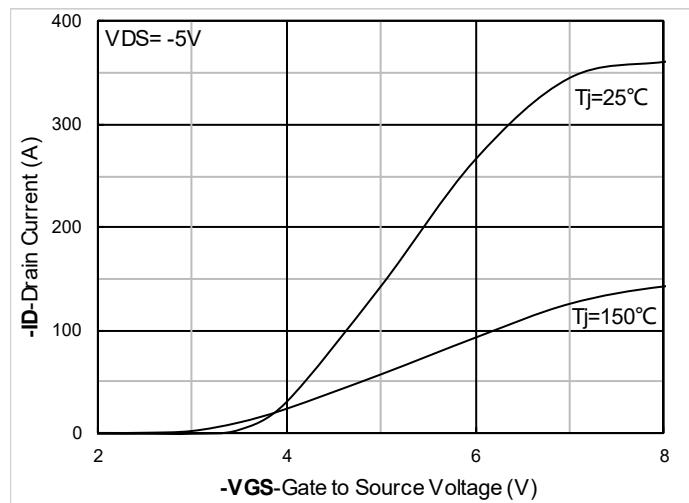


Figure 2. Transfer Characteristics

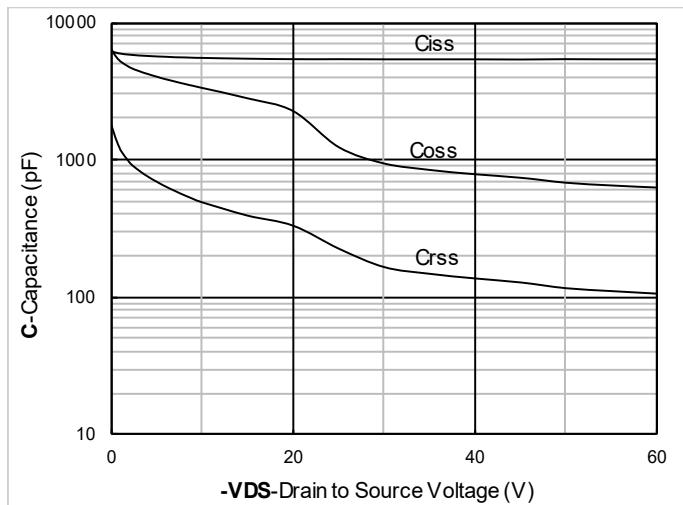


Figure 3. Capacitance Characteristics

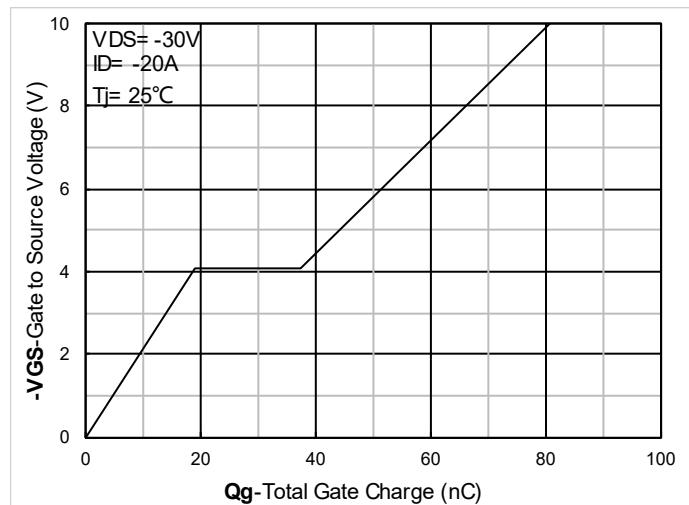


Figure 4. Gate Charge

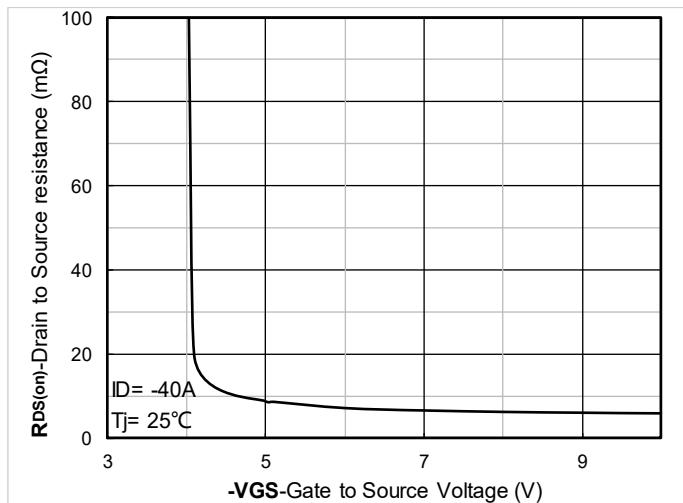


Figure 5. On-Resistance vs Gate to Source Voltage

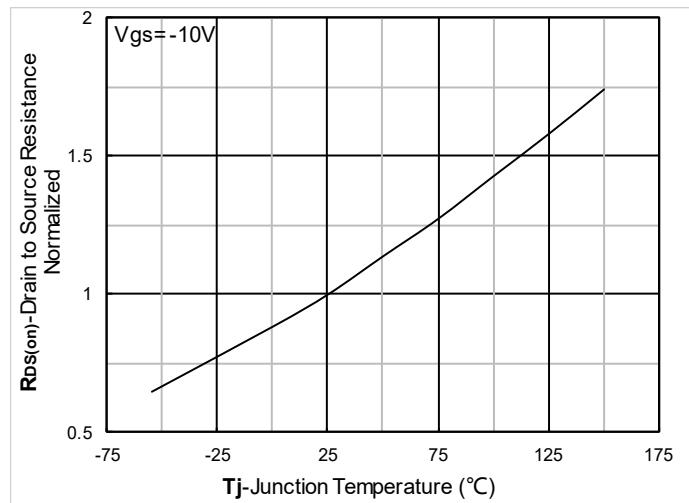
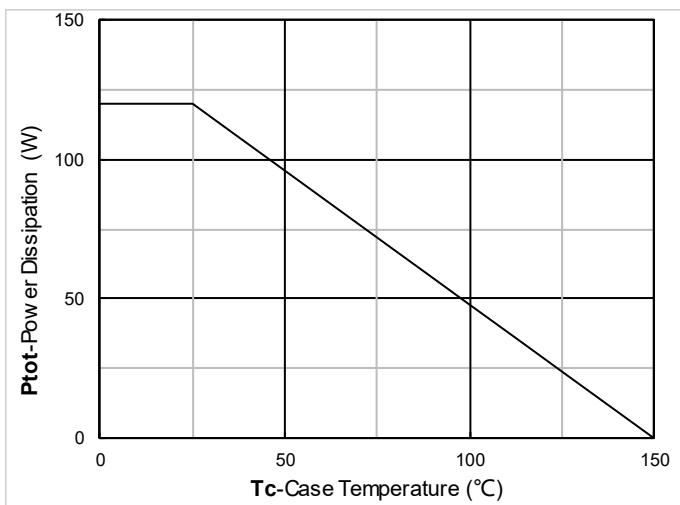
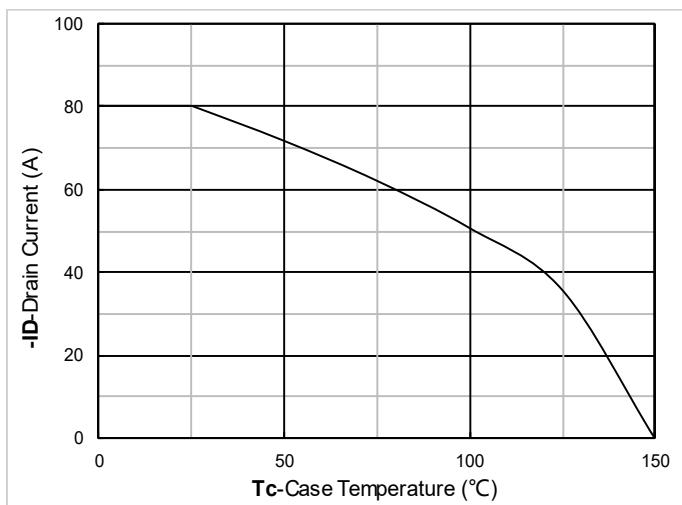
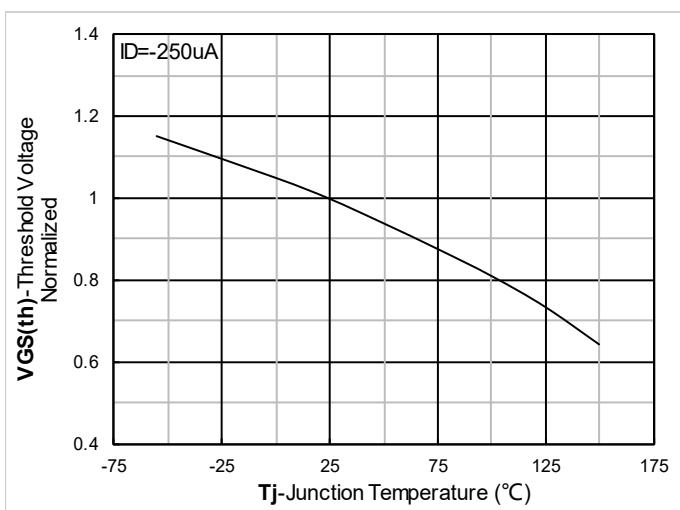
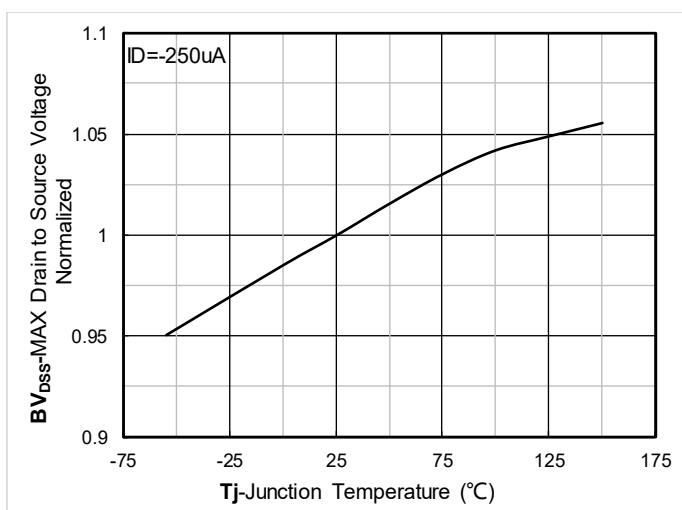
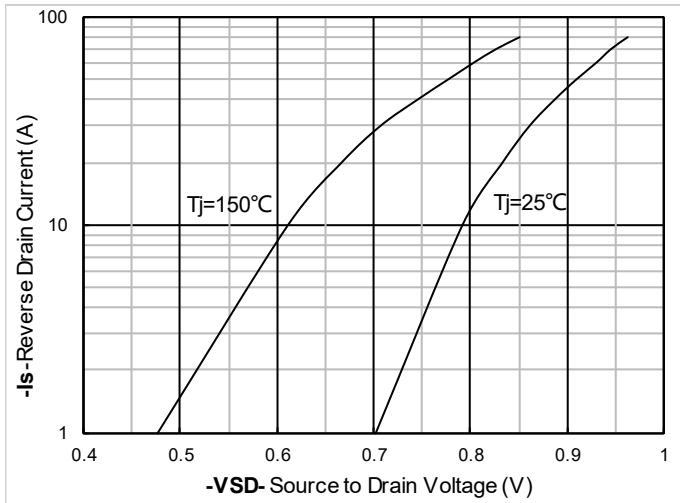
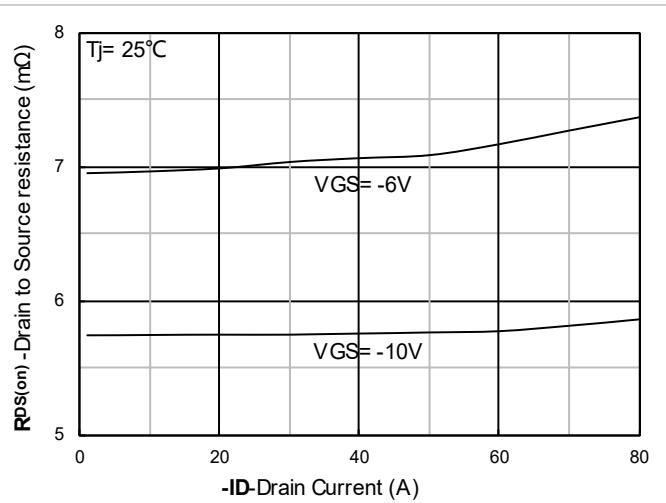


Figure 6. Normalized On-Resistance





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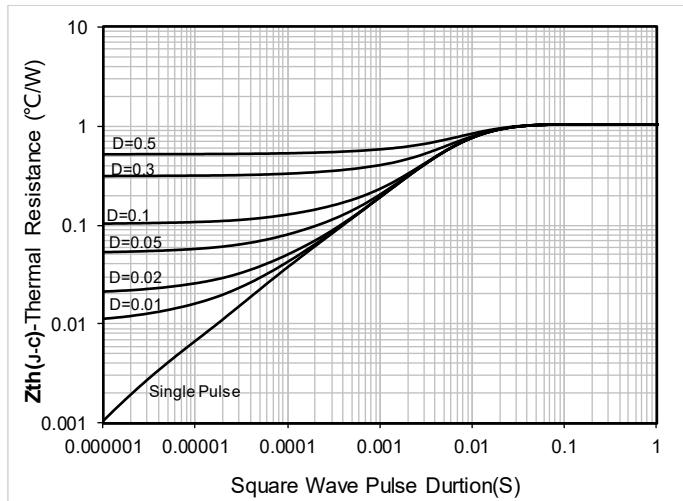


Figure 13. Maximum Transient Thermal Impedance

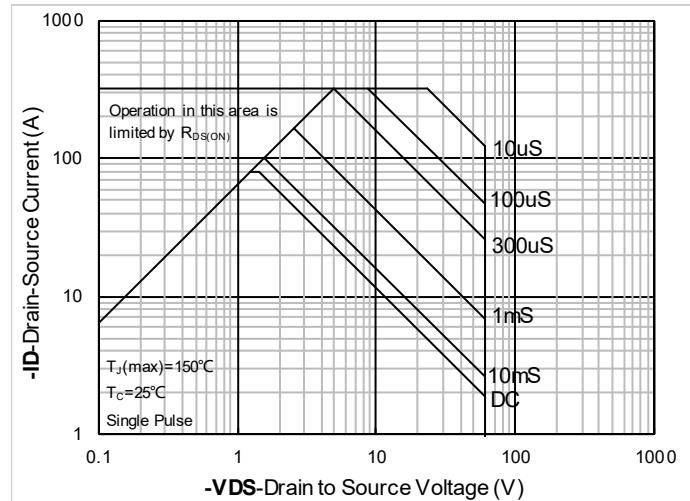
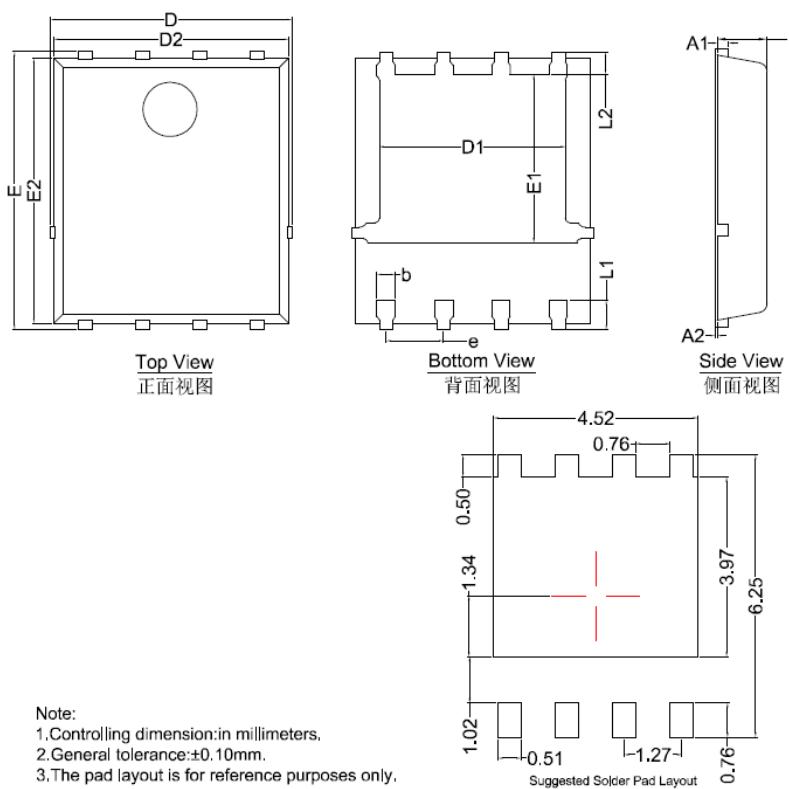


Figure 14. Safe Operation Area



■ Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1		0.254 BSC	
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
L1	0.56	0.66	0.76
L2		0.50 BSC	
b	0.31	0.41	0.51
e		1.27 BSC	

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.10\text{mm}$.
3. The pad layout is for reference purposes only.



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